



FAX NO.

P. 01/03

Customer No.: 31561  
Docket No.: 10790-US-PA  
Application No.: 10/709,588

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Chen et al.  
Application No. : 10/709,588  
Filed : 2004/5/17  
For : FLIP CHIP PACKAGE AND MANUFACTURING METHOD  
THEREOF  
Art Unit : 2812  
Examiner : GEYER, SCOTT B

**TRANSMITTAL LETTER**

002-1-571-273-2885

(Via fax : 1+2 pages)

Assistant Commissioner for Patents  
Alexandria, VA 22314

Dear Sir,

In response to the Notice of Allowance and Fee(s) due, dated September 14, 2006, transmitted herewith please find the Issue Fee Transmittal (PTOL-85B) in duplicate.

Please charge the fee in the amount of \$1700.00 for Issue Fee and Publication Fee to Account No. 50-2620 (Order No.: 10790-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date : Dec 5, 2006

By : Belinda Lee  
Belinda Lee  
Registration No.: 46,863

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